#### 503162853 02/03/2015

### PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
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EIKO OKAMOTO	01/27/2015
HIROSHI ONOMOTO	01/27/2015
JITSUO HIROHATA	01/27/2015
YUJI MATSUBARA	01/27/2015
HIDEKI MASUDA	01/27/2015

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#### **PROPERTY NUMBERS Total: 1**

Property Type	Number	
Application Number:	14419293	

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PATENT REEL: 034875 FRAME: 0039

503162853

ATTORNEY DOCKET NUMBER:	7412/134410
NAME OF SUBMITTER:	LOIS FORD
SIGNATURE:	/Lois Ford/
DATE SIGNED:	02/03/2015
	This document serves as an Oath/Declaration (37 CFR 1.63).
Total Attachments: 4 source=Assignment#page1.tif source=Assignment#page2.tif source=Assignment#page3.tif source=Assignment#page4.tif	

PATENT REEL: 034875 FRAME: 0040 Fitch, Even, Tabin & Flannery LLP 1250 23rd Street, NW, Suite 410 Washington, DC 20037 USA Patent Appln.

For inventions made outside USA executed with or after application Atty. Dkt. 7412/134410

REEL: 034875 FRAME: 0041

# NONPROVISIONAL ASSIGNMENT WITH DECLARATION NONPROVISIONAL OF NONPROVISIONAL APPLICATION

Sole or Joint

	·	
INSERT	(1) Masashi IKAWA	(2) Eiko OKAMOTO
NAME(S) OF INVENTOR(S)	(3) Hiroshi ONOMOTO	(4) <u>Jitsuo HIROHATA</u>
·	(5) Yuji MATSUBARA	(6) <u>Hideki MASUDA</u>
the receipt and suffic assign(s) and transfer	iency of which are hereby acknowledge (s) unto:	ed by the undersigned who at the request of, hereby sell(s)
INSERT Mits NAME(S) OF	ubishi Rayon Co., Ltd.	
ASSIGNEE(S) 1-1,	Marunouchi 1-chome, Chiyoda-ku,	Гокуо 100-8253 Јарап
& ADDRESS(ES)_		
INCEDT V.~	agawa Academy of Science and Tech	nology
NEA WARRION AND		
ASSIGNEE(S) 2-1.	Sakado 3-chome, Takatsu-ku, Kawa	saki-shi, Kanagawa 213-0012 Japan
& ADDRESS(ES)_		
as:		ssues, and reexaminations thereof; and all resulting patents, know
as: OD OF MANUFACTURING N	MOLD, AND MOLDED ARTICLE HAVING FINE REL	EF STRUCTURE ON SURFACE AND METHOD OF MANUFACTURING THE atents of the United States of America:
as:  OD OF MANUFACTURING N  NOTE	for which an application for Letters P  (A)  was filed on even date here	ef STRUCTURE ON SURFACE AND METHOD OF MANUFACTURING THE atents of the United States of America:  with
as: OD OF MANUFACTURING N	for which an application for Letters P  (A)  was filed on even date here	EF STRUCTURE ON SURFACE AND METHOD OF MANUFACTURING THE atents of the United States of America:  with
NOTE  (Complete line A, B and/or C)  AND I hereby the above-identified at disclose information w and (4) I believe I at acknowledge that any of not more than five ( AND the und issue said Letters Pate AND the und ASSIGNEE; AND the und representatives, deemed	for which an application for Letters P  (A) was filed on even date here (B) executed on (C) was filed on my behalf as  Declare (1) the above-identified application and understand the contents of thich is known to me to be material to paten in the original inventor or an original join willful false statement in the aforesaid Declarical inventor of the said ASSIGNEE, for its interest and dersigned hereby authorize(s) and request (and to the said ASSIGNEE, for its interest and dersigned hereby agree(s) to testify and executed essential by ASSIGNEE to ASSIGNEE=  med hereby authorize(s) Fitch, Even, Tabe	atents of the United States of America:  with  PCT/JP2013/071223, filed August 6, 2013,  on was made or authorized to be made by me; (2) I have reviewed the above-identified specification; (3) I acknowledge the duty of tability as defined in Title 37, Code of Federal Regulations, §1.5 and inventor of a claimed invention in this application. I hereby tration is punishable under 18 U.S.C. 1001 by fine or imprisonments and the United States Commissioner of Patents and Trademarks and SASSIGNEE, its successors, assigns and legal representatives; accord in said application shall hereinafter act on behalf of said specification and title in and to the invention hereby transferred in & Flannery of the above address to insert hereon any further
NOTE (Complete line A, B and/or C)  AND I hereby the above-identified a disclose information w and (4) I believe I an acknowledge that any of not more than five ( AND the und issue said Letters Pate AND the und representatives, deemed  NOTE) The undersigned identification necessariance.	for which an application for Letters P  (A) was filed on even date here (B) executed on (C) was filed on my behalf as  Declare (1) the above-identified application and understand the contents of hich is known to me to be material to paten in the original inventor or an original joi willful false statement in the aforesaid Declarical inventor of the said ASSIGNEE, for its interest and dersigned hereby authorize(s) and request (and to the said ASSIGNEE, for its interest and dersigned hereby agree(s) to testify and except descential by ASSIGNEE to ASSIGNEE and hereby authorize(s) Fitch, Even, Tabry or desirable for recordation of this document of the said hereby authorize(s).	atents of the United States of America:  with  PCT/JP2013/071223, filed August 6, 2013,  on was made or authorized to be made by me; (2) I have reviewed the above-identified specification; (3) I acknowledge the duty thability as defined in Title 37, Code of Federal Regulations, §1.5 and inventor of a claimed invention in this application. I herefuration is punishable under 18 U.S.C. 1001 by fine or imprisonments and the United States Commissioner of Patents and Trademarks and ASSIGNEE, its successors, assigns and legal representatives; second in said application shall hereinafter act on behalf of safetute any papers for ASSIGNEE, its successors, assigns and legal secute any papers for ASSIGNEE, its successors, assigns and legal for safetute any papers for ASSIGNEE, its successors, assigns and legal secute any papers for ASSIGNEE, its successors, assigns and legal for safetute any papers for ASSIGNEE, its successors, assigns and legal for safetute any papers for ASSIGNEE, its successors, assigns and legal for safetute any papers for ASSIGNEE, its successors, assigns and legal for safetute any papers for ASSIGNEE, its successors, assigns and legal for safetute any papers for ASSIGNEE, its successors assigns and legal for safetute any papers for ASSIGNEE, its successors assigns and legal for safetute any papers for ASSIGNEE, its successors assigns and legal for safetute any papers for ASSIGNEE, its successors assigns and legal for safetute any papers for ASSIGNEE, its successors assigns and legal for safetute any papers for ASSIGNEE, its successors assigns and legal for safetute any papers for ASSIGNEE, its successors assigns and legal for safetute any papers for ASSIGNEE, its successors assigns and legal for safetute any papers for ASSIGNEE, its successors assigns and legal for safetute any papers for ASSIGNEE, its successors assigns and legal for safetute any papers for ASSIGNEE, its successors assigns and legal for safetute any papers for ASSIGNEE, its successors assigns and legal for safetute any papers for AS
NOTE  (Complete line A, B and/or C)  AND I hereby the above-identified at disclose information w and (4) I believe I at acknowledge that any of not more than five ( AND the und issue said Letters Pate AND the und ASSIGNEE; AND the und representatives, deemed	for which an application for Letters P  (A) was filed on even date here (B) executed on (C) was filed on my behalf as  Declare (1) the above-identified application and understand the contents of thich is known to me to be material to paten the original inventor or an original join willful false statement in the aforesaid Declarication and ASSIGNEE, for its interest and dersigned hereby authorize(s) and request(and to the said ASSIGNEE, for its interest and dersigned hereby agree(s) to testify and except descential by ASSIGNEE to ASSIGNEE=  med hereby authorize(s) Fitch, Even, Tabry or desirable for recordation of this documents.	atents of the United States of America:  with  PCT/JP2013/071223, filed August 6, 2013,  on was made or authorized to be made by me; (2) I have reviewed the above-identified specification; (3) I acknowledge the duty tability as defined in Title 37, Code of Federal Regulations, §1.5 nt inventor of a claimed invention in this application. I hereby training is punishable under 18 U.S.C. 1001 by fine or imprisonments, ASSIGNEE, its successors, assigns and legal representatives; ecord in said application shall hereinafter act on behalf of said cute any papers for ASSIGNEE, its successors, assigns and legal representatives; Said protection and title in and to the invention hereby transferred in & Flannery of the above address to insert hereon any furthment.

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Name: Inventor's signature: Date:	Hiroshi ONOMOTO  January 27, 2015		
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Name: Inventor's signature: Date: Residence:	Hideki MASUDA		
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	Tanatou-nu, Itawaouni-oni, Itanayawa & 10-00 in outsin		

PATENT REEL: 034875 FRAME: 0042 Fitch, Even, Tabin & Flannery LLP 1250 23rd Street, NW, Suite 410 Washington, DC 20037 For inventions made outside USA executed with or after application Atty. Dkt. 7412/134410

USA Patent Appln. Sole or Joint

## NONPROVISIONAL ASSIGNMENT WITH DECLARATION NONPROVISIONAL OF NONPROVISIONAL APPLICATION

In consideration of the sum of Ten Dollars (\$10.00) and other good and valuable consideration paid to each of the undersigned, to wit:

INSERT	(1) <u>Masashi IK</u>	AWA	(2) Eiko OKAMOTO
NAME(S) OF INVENTOR(S)	(3) <u>Hiroshi ON</u>	омото	(4) <u>Jitsuo HIROHATA</u>
	(5) <u>Yuji MATS</u>	UBARA	(6) Hideki MASUDA
assign(s) and transfe	•		by the undersigned who at the request of, hereby sell
NAME(S) OF			
			kyo 100-8253 Japan
NAME(S) OF_ ASSIGNEE(S) 2-1,	Sakado 3-chome,		ology si-shi, Kanagawa 213-0012 Japan
applications including as:	any divisions, continua	ations, substitutes, reissue	erest for the United States of America, in the invention and es, and reexaminations thereof; and all resulting patents, known of the structure on surface and method of manufacturing.
			nts of the United States of America:
NOTE	• •	on even date herewit	ch c
(Complete line A, B and/or C)	(C) was filed	on I on my behalf as PC	T/JP2013/071223, filed August 6, 2013,
the above-identified a disclose information wand (4) I believe I at acknowledge that any of not more than five (AND the undissue said Letters Pate AND the unASSIGNEE;	pplication and undersiblich is known to me to m the original inventor willful false statement if (5) years, or both; dersigned hereby author to the said ASSIGN dersigned agree(s) the	tand the contents of the be material to patentable or or an original joint in the aforesaid Declaration orize(s) and request(s) the EE, for its interest as AS at the attorney of record	was made or authorized to be made by me; (2) I have review above-identified specification; (3) I acknowledge the durility as defined in Title 37, Code of Federal Regulations, §1 inventor of a claimed invention in this application. I her on is punishable under 18 U.S.C. 1001 by fine or imprisonmine United States Commissioner of Patents and Trademark SSIGNEE, its successors, assigns and legal representatives; d in said application shall hereinafter act on behalf of see any papers for ASSIGNEE, its successors, assigns and legal representatives;
			e any papers for ASSIGNEE, its successors, assigns and it ill protection and title in and to the invention hereby transfer.
		(s) Fitch, Even, Tabin & ordation of this document	& Flannery of the above address to insert hereon any fur- t.
Name: Inventor's signatur		Masashi IKAWA	
Date:			PATENT
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**RECORDED: 02/03/2015**